

64-pin, 9mm x 9mm QFN Package and Recommended PCB Solder Pad Information

Package Information

The device is offered in a 9 mm x 9 mm, 64-pin, QFN leadless package with a 0.5 mm lead pitch. This package has an exposed ground paddle on the bottom of the package which must be soldered to the ground plane of the printed circuit board. The paddle is important for thermal dissipation as well as electrical grounding performance. The leads and the ground paddle are finished with 100 % matte-Sn and constructed using Green materials and is RoHS compliant. The complete RoHS test report is available online <http://www.scintera.com/pdfs/RoHS-2529440-Scintera-Networks-Inc.pdf>.

THERMAL RESISTANCE CHARACTERISTICS

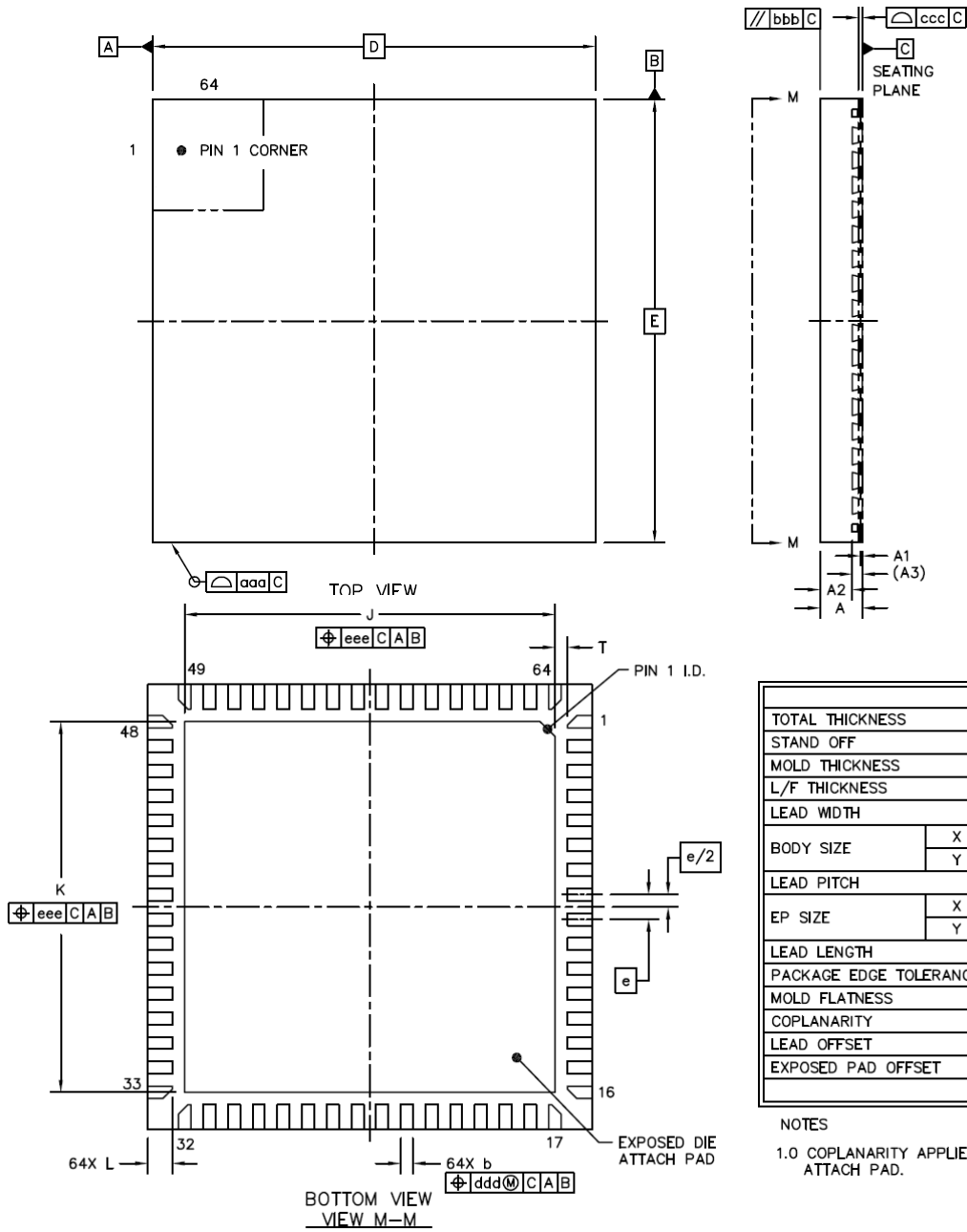
| PARAMETER | SYMBOL | CONDITIONS | TYP | UNITS |
|-------------------------------------|---------------|------------|-----|-------|
| Junction to Case Thermal Resistance | Θ_{JC} | Still Air | 0.8 | °C/W |

MOISTURE SENSITIVITY LEVEL (MSL)

| TEST METHODOLOGY | RATING | PACKAGE PEAK TEMPERATURE | UNITS |
|------------------|--------|--------------------------|-------|
| Per JESD22-A113 | 3 | 260 | °C |

COUNTRY OF ORIGIN: Taiwan

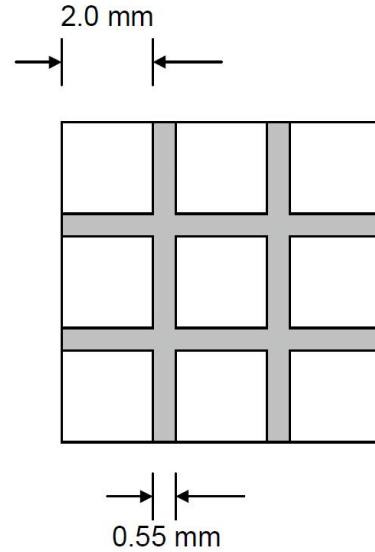
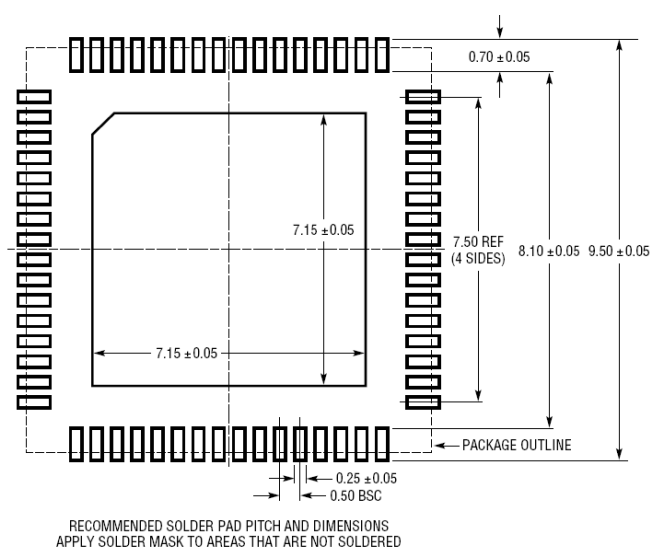
PACKAGE MECHANICAL DIMENSIONS



| | SYMBOL | MIN | NOM | MAX | |
|------------------------|--------|-----------|-------|------|-----|
| TOTAL THICKNESS | A | 0.8 | 0.85 | 0.9 | |
| STAND OFF | A1 | 0 | 0.035 | 0.05 | |
| MOLD THICKNESS | A2 | --- | 0.65 | 0.67 | |
| L/F THICKNESS | A3 | 0.203 REF | | | |
| LEAD WIDTH | b | 0.2 | 0.25 | 0.3 | |
| BODY SIZE | X | 9 BSC | | | |
| | Y | 9 BSC | | | |
| LEAD PITCH | e | 0.5 BSC | | | |
| EP SIZE | X | J | 7.4 | 7.5 | 7.6 |
| | Y | K | 7.4 | 7.5 | 7.6 |
| LEAD LENGTH | L | 0.45 | 0.5 | 0.55 | |
| PACKAGE EDGE TOLERANCE | aaa | 0.1 | | | |
| MOLD FLATNESS | bbb | 0.1 | | | |
| COPLANARITY | ccc | 0.08 | | | |
| LEAD OFFSET | ddd | 0.1 | | | |
| EXPOSED PAD OFFSET | eee | 0.1 | | | |
| | T | 0.15 | 0.25 | 0.35 | |

NOTES
 1.0 COPLANARITY APPLIES TO LEADS, CORNER LEADS AND DIE ATTACH PAD.

RECOMMENDED PCB SOLDER PAD LAYOUT



Additional information regarding quality, reliability, package and environmental information can be found online at <http://www.scintera.com/resource-center/quality-reliability-package-environmental-information/>.

Additional information regarding layout of IC and of system may be found in the respective IC's Hardware Design Guide.

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